



(0.635 mm) .025"

MIS SERIES

MIXED TECHNOLOGY SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MIS

Insulator Material:
Liquid Crystal Polymer

Contact Material:
Phosphor Bronze

Plating:

Au or Sn over

50 μ " (1.27 μ m) Ni

Operating Temp Range:

-55 °C to +125 °C

Voltage Rating:

275 VAC

Max Cycles:

100

RoHS Compliant:

Yes

Processing:

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (019-057)

Board Stacking:

For applications requiring more

than two connectors per board

contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- 11 mm, 16 mm, 18.75 mm and 22 mm stack height
- 30 μ " (0.76 μ m) Gold
- Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
- 76, 95, 114 and 133 positions per row

Contact Samtec.

Board Mates:

MIT

Cable Mates:

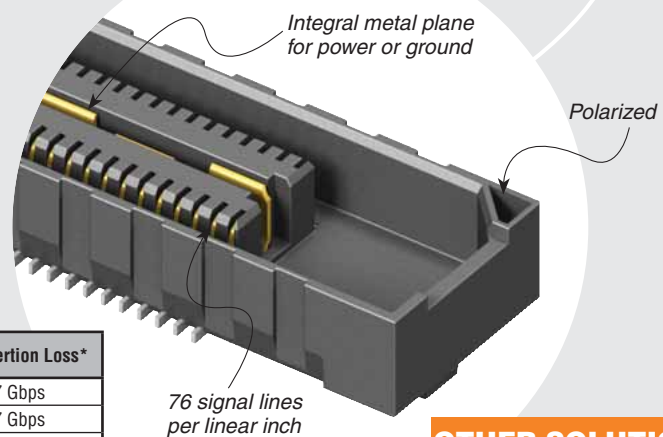
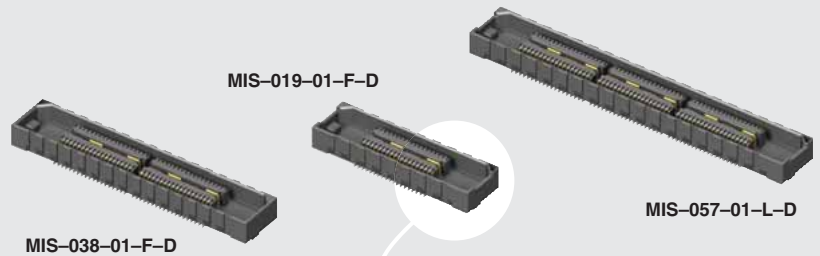
MICD



- Mixed technology footprint

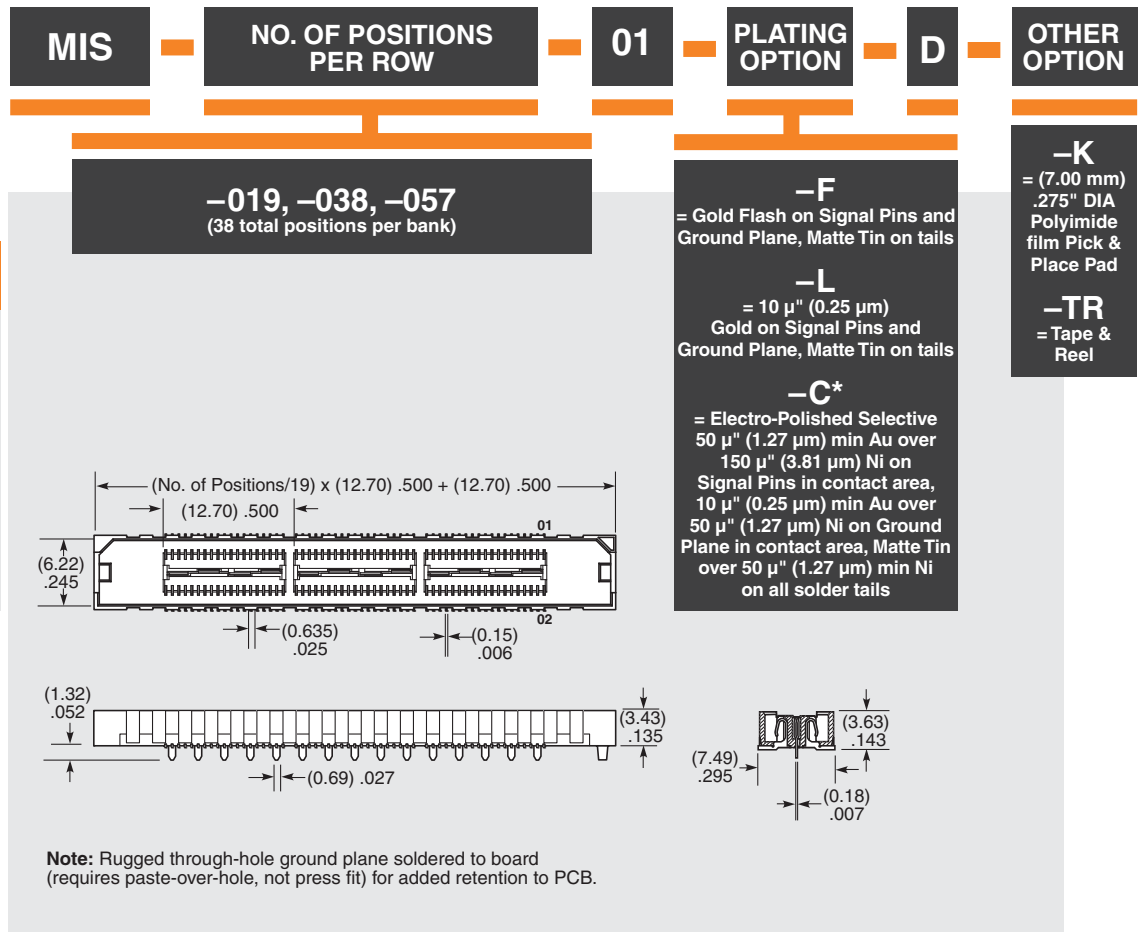
MIT/MIS 5 mm Stack Height	Type	Rated @ 3dB Insertion Loss*
Single-Ended Signaling	-D	8.5 GHz / 17 Gbps
Differential Pair Signaling	-D	8.5 GHz / 17 Gbps
Differential Pair Signaling	-DP	9.5 GHz / 19 Gbps

*Performance data includes effects of a non-optimized PCB.
Performance data for other stack heights and complete test data available at www.samtec.com?MIS or contact sig@samtec.com



OTHER SOLUTIONS

- Board Spacing Standoffs. See SO Series.



*Note: -C Plating passes 10 year MFG testing

Note: Some lengths, styles and options are non-standard, non-returnable.